

Statement

We Quectel Wireless Solutions Co., Ltd. declare the following models.

Product Name: LTE Module

Model Number: EG915-LA

Hardware Version: R1.1

The revised R1.1 version of EG915U-LA has no changes in frequency bands.

There are three small changes as follows.

1. PCB laminated structure change: from 8 layers 1 step to 10 layers 1 step.

Old:

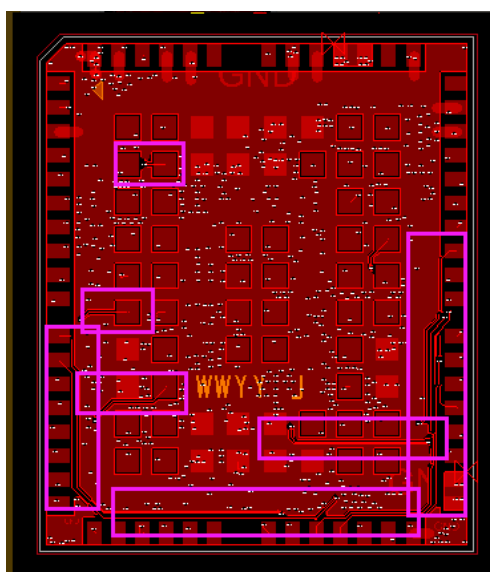
Layer	Mother Board	Tolerance (um)	Thickness (um)	Die	DF	材料型号	材料规格	结构图
L1	Solder Mask	+/-5	30	NA	NA			
L1	copper-plating	+/-5	30	NA	NA			
L2	Prepreg/DRG	+/-7.0	52	0.80	0.010	S1150GB	#106 RCT4%	
L2	copper-plating	+/-5	23	NA	NA			
L3	Prepreg	+/-10%	122	4.1	0.012	S1150GB	#116 RCT5%	
L3	Copper	Haz	16	NA	NA			
L4	Core	+/-13	75	3.8	0.014	S1150G	0.075mm H/H	
L4	Copper	Haz	16	NA	NA			
L5	Prepreg	+/-10%	122	4.1	0.012	S1150GB	#116 RCT5%	
L5	Copper	Haz	16	NA	NA			
L6	Core	+/-13	75	3.8	0.014	S1150G	0.075mm H/H	
L6	Copper	Haz	16	NA	NA			
L7	Prepreg	+/-10%	122	4.1	0.012	S1150GB	#116 RCT5%	
L7	copper-plating	+/-5	23	NA	NA			
L8	Prepreg	+/-7.0	52	0.80	0.010	S1150GB	#106 RCT4%	
L8	copper-plating	+/-5	30	NA	NA			
	Solder Mask	+/-5	30	NA	NA			
Total thickness(Drill-Dr)		0.8+-0.08mm	830					

New:

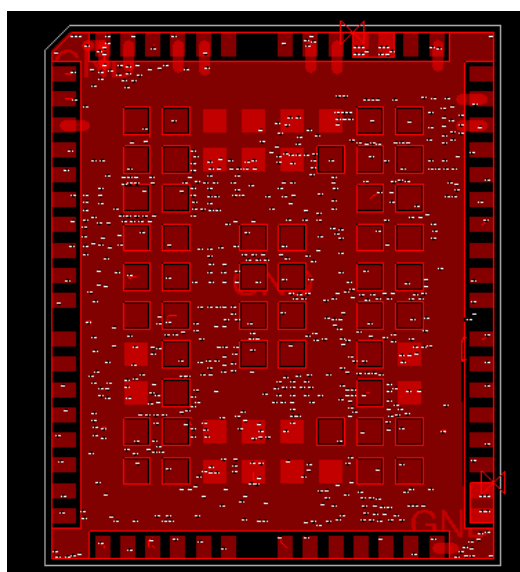
Layer	Mother Board	Typical layer thickness(um)	Tolerance (um)	Dielectric Constant	DF	材料型号	材料规格	结构图
L1	Solder Mask	30	+/-0.15	3.5	0.016			
L1	copper-plating	21	+/-6	NA	NA			
L2	Prepreg/DRG	48	+/-13	3.5	0.016	S1150GB	#106 RCT4%	
L2	copper-plating	21	+/-6	NA	NA			
L3	Prepreg/DRG	48	+/-13	3.5	0.016	S1150GB	#106 RCT4%	
L3	Copper Hoz	15	+/-5	NA	NA			
L4	Core	75	+/-15	3.8	0.014	S1150G	0.075mm H/H	
L4	Copper Hoz	15	+/-5	NA	NA			
L5	Prepreg/DRG	70	+/-15	3.8	0.013	S1150GB	#106 RCT4%	
L5	Copper Hoz	15	+/-5	NA	NA			
L6	Core	75	+/-15	3.8	0.014	S1150G	0.075mm H/H	
L6	Copper Hoz	15	+/-5	NA	NA			
L7	Prepreg/DRG	70	+/-15	3.8	0.013	S1150GB	#106 RCT4%	
L7	Copper Hoz	15	+/-5	NA	NA			
L8	Core	75	+/-15	3.8	0.014	S1150G	0.075mm H/H	
L8	Copper Hoz	15	+/-5	NA	NA			
L9	Prepreg/DRG	48	+/-13	3.5	0.016	S1150GB	#106 RCT4%	
L9	copper-plating	21	+/-6	NA	NA			
L10	copper-plating	21	+/-6	NA	NA			
	Solder Mask	30	+/-0.15	3.5	0.016			
Total thickness		700	0.8+-0.10mm					

2. There was wiring on the bottom surface before, now delete the wiring on the bottom surface.

Old:

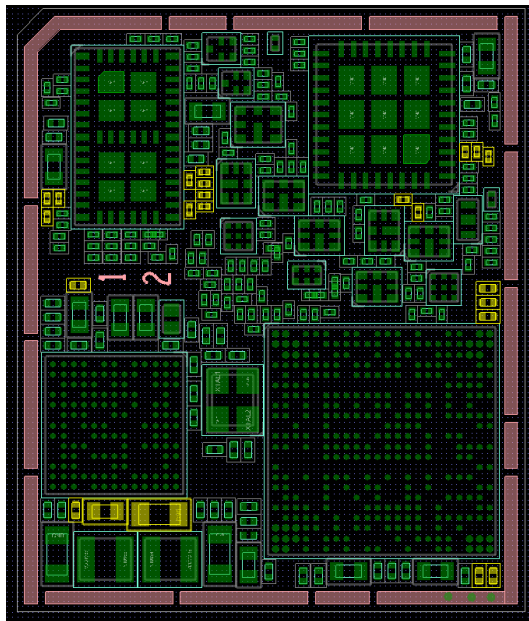


New:

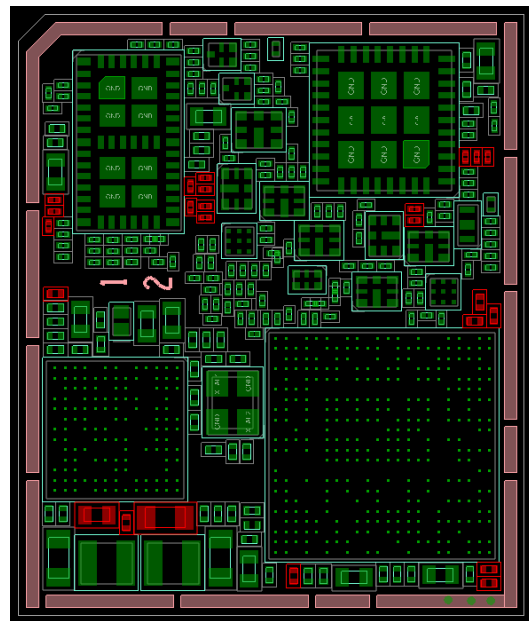


3. The device position is changed.

Old:



New:



Request for Class II Permissive Change

FCC ID: XMR202111EG915ULA / Grant Date: 12/02/2021

Pursuant to CFR2.104, Quectel Wireless Solutions Co., Ltd hereby requests a Class III Permissive Change

Your assistance on this matter is highly appreciated.

Signature

Printed Name

Jean Hu

Date: 2022-02-18

Title:

Tel: